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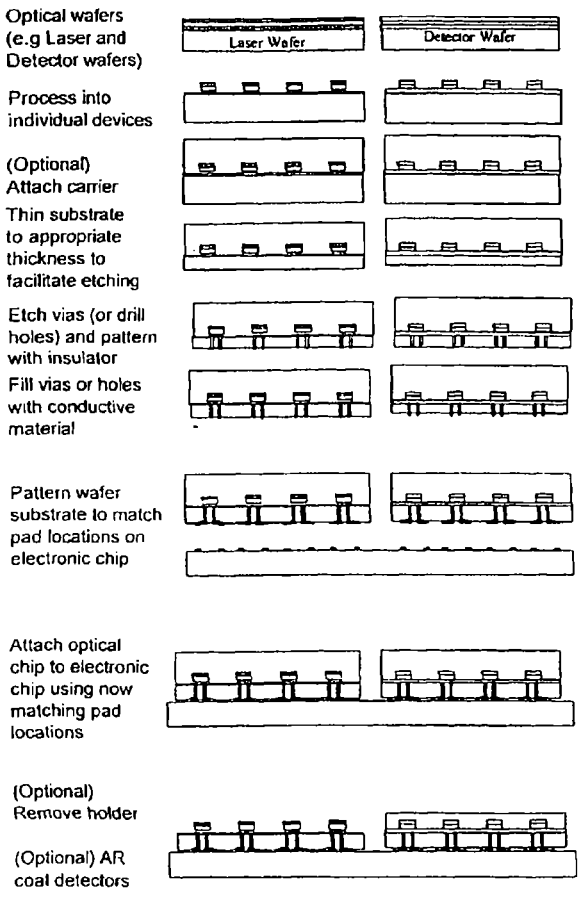
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(54) Title: OPTO-ELECTRONIC DEVICE INTEGRATION



(57) Abstract: A method of integrating a chip with a topside optical chip has at least one optical device, having an active side including an optically active region, a laser cavity having a height, an optically inactive region, a bonding side opposite the active side, and a device thickness. The method involves bonding the optical chip to the electronic chip; appying a substrate to the active side, the substrate having a substrate thickness over the active region in the range of between a first amount and a second amount, and applying an antireflection without a special patterning or distinguishing between the at least one optical laser device and the other device.



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